

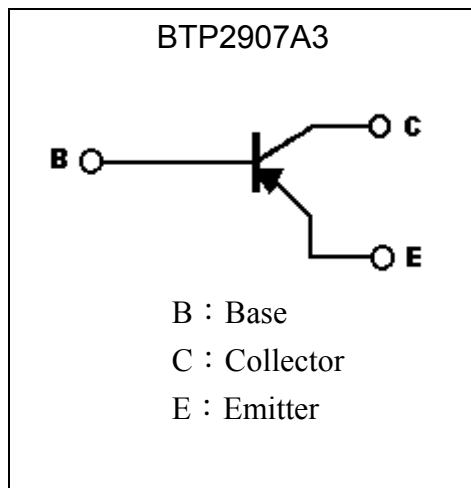
General Purpose PNP Epitaxial Planar Transistor

BTP2907A3

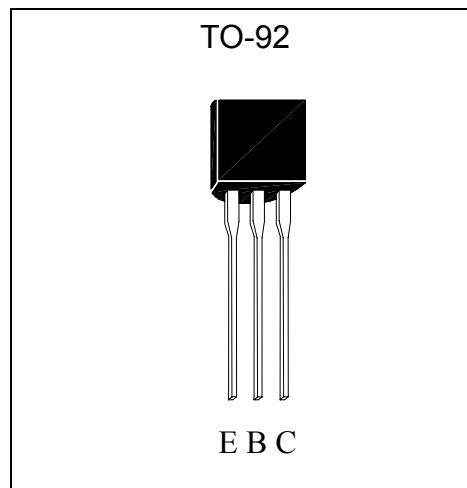
Description

- The BTP2907A3 is designed for general purpose amplifier and high-speed switching, medium power applications.
- Low collector saturation voltage
- High speed switching.
- Complementary to BTN2222A3
- Pb-free package

Symbol



Outline



Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V _{CBO}	-60	V
Collector-Emitter Voltage	V _{CEO}	-60	V
Emitter-Base Voltage	V _{EB0}	-5	V
Collector Current	I _C	-600	mA
Power Dissipation	P _d	625	mW
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55~+150	°C

**Characteristics (Ta=25°C)**

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CBO}	-60	-	-	V	I _C =-10μA
BV _{CEO}	-60	-	-	V	I _C =-10mA
BV _{EBO}	-5	-	-	V	I _E =-10μA
I _{CBO}	-	-	-10	nA	V _{CB} =-50V
I _{CEX}	-	-	-50	nA	V _{CE} =-30V, V _{BE(OFF)} =-0.5V
*V _{CE(sat)}	-	-0.2	-0.4	V	I _C =-150mA, I _B =-15mA
*V _{CE(sat)}	-	-0.5	-1.6	V	I _C =-500mA, I _B =-50mA
*V _{BE(sat)}	-	-	-1.3	V	I _C =-150mA, I _B =-15mA
*V _{BE(sat)}	-	-	-2.6	V	I _C =-500mA, I _B =-50mA
*h _{FE 1}	75	-	-	-	V _{CE} =-10V, I _C =-100μA
*h _{FE 2}	100	-	-	-	V _{CE} =-10V, I _C =-1mA
*h _{FE 3}	100	-	-	-	V _{CE} =-10V, I _C =-10mA
*h _{FE 4}	100	-	300	-	V _{CE} =-10V, I _C =-150mA
*h _{FE 5}	50	-	-	-	V _{CE} =-10V, I _C =-500mA
f _T	200	-	-	MHz	V _{CE} =-20V, I _C =-50mA, f=100MHz
Cob	-	-	8	pF	V _{CB} =-30V, I _E =0A, f=1MHz

*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

Classification Of h_{FE4}

Rank	A	N	B
Range	100~180	120~270	180~300

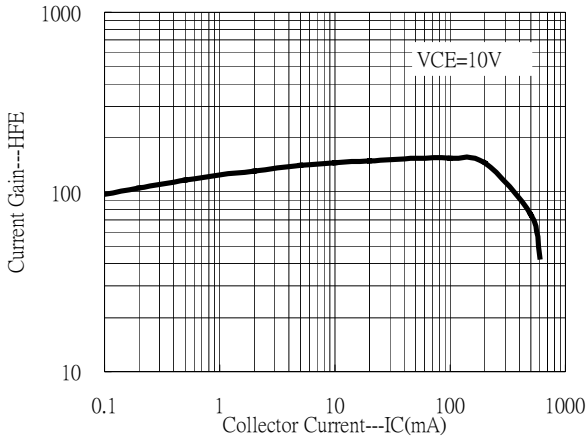
Ordering Information

Device	Package	Shipping
BTP2907A3	TO-92 (Pb-free)	2000 pcs / Tape & Box

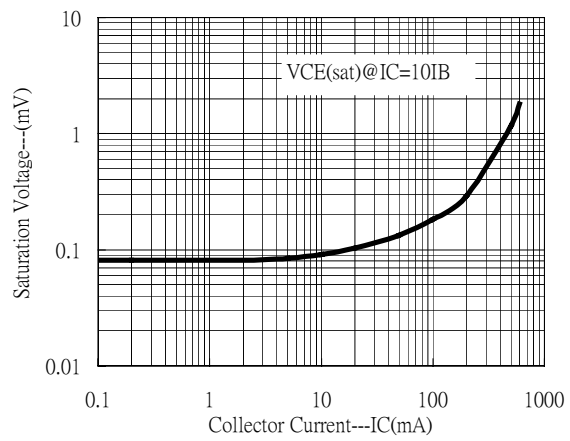


Characteristic Curves

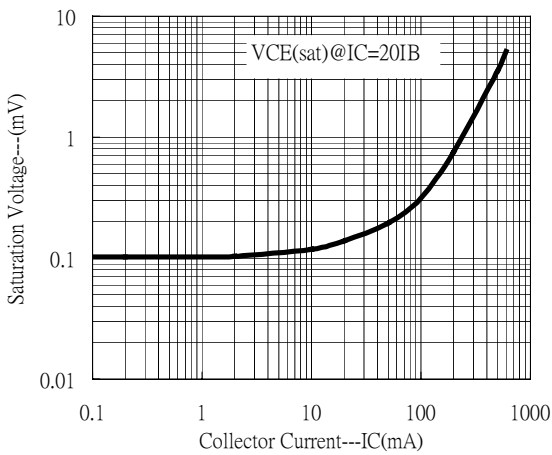
Current Gain vs Collector Current



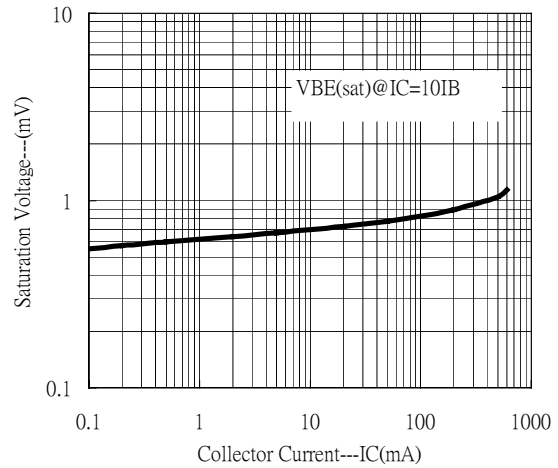
Saturation Voltage vs Collector Current



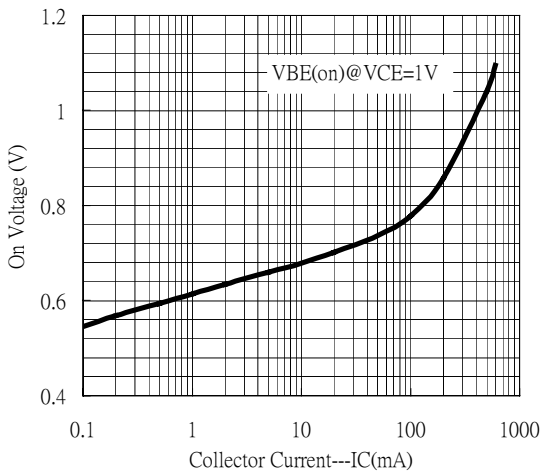
Saturation Voltage vs Collector Current



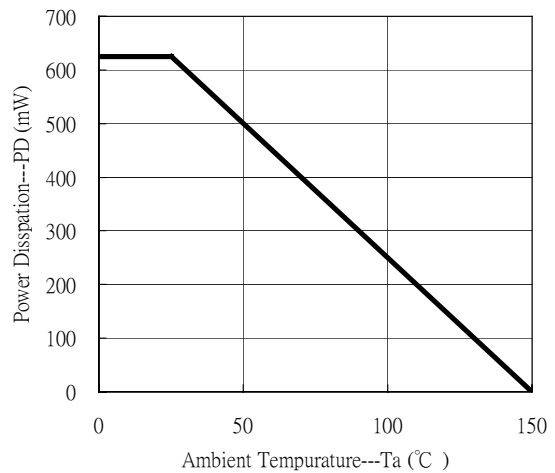
Saturation Voltage vs Collector Current



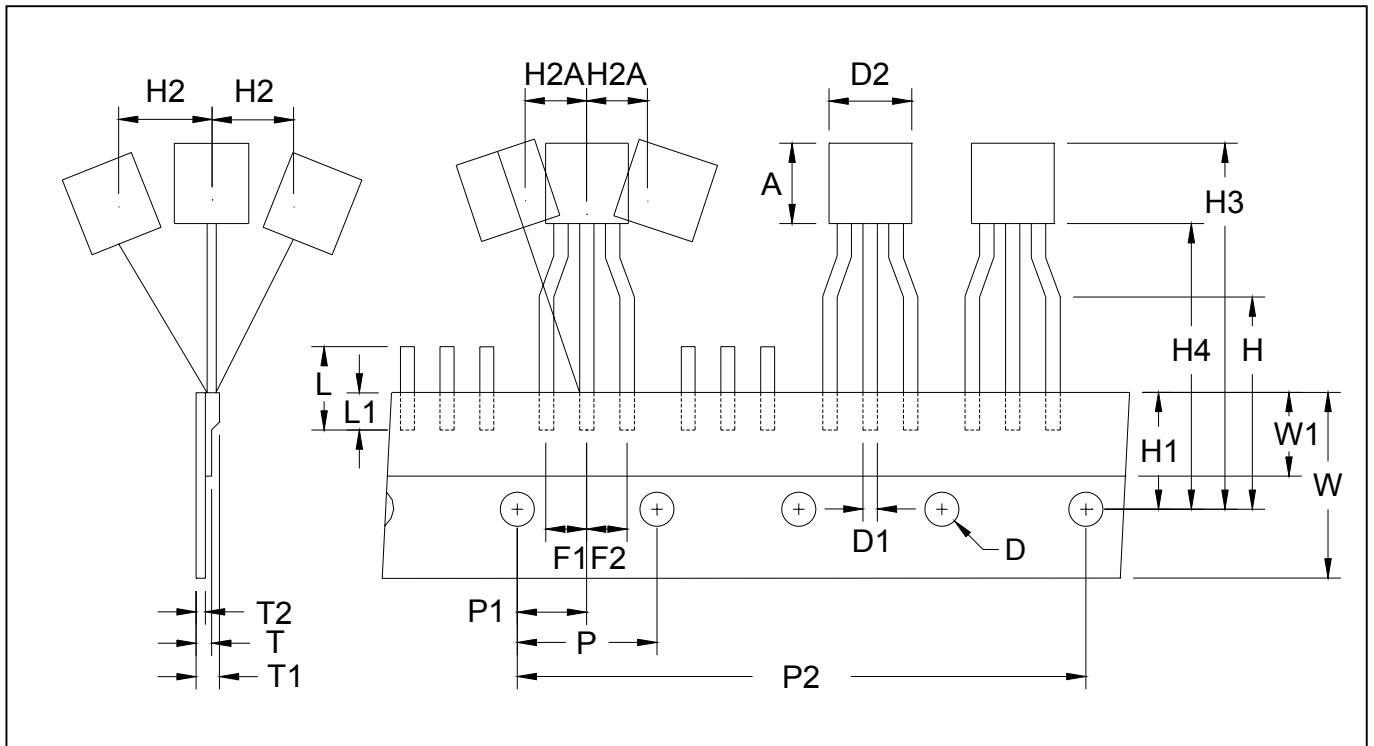
On Voltage vs Collector Current



Power Derating Curve

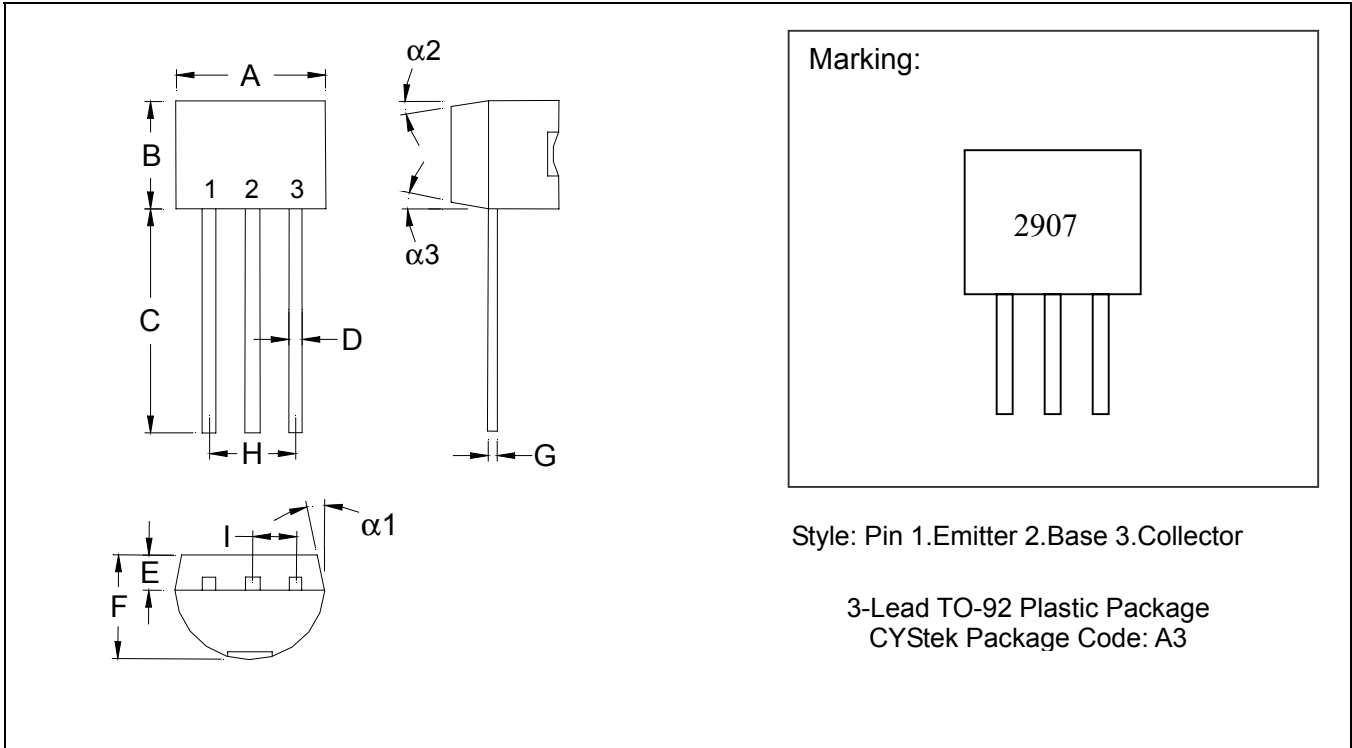


TO-92 Taping Outline



DIM	Item	Millimeters	
		Min.	Max.
A	Component body height	4.33	4.83
D	Tape Feed Diameter	3.80	4.20
D1	Lead Diameter	0.36	0.53
D2	Component Body Diameter	4.33	4.83
F1,F2	Component Lead Pitch	2.40	2.90
F1,F2	F1-F2	-	±0.3
H	Height Of Seating Plane	15.50	16.50
H1	Feed Hole Location	8.50	9.50
H2	Front To Rear Deflection	-	1
H2A	Deflection Left Or Right	-	1
H3	Component Height	-	27
H4	Feed Hole To Bottom Of Component	-	21
L	Lead Length After Component Removal	-	11
L1	Lead Wire Enclosure	2.50	-
P	Feed Hole Pitch	12.50	12.90
P1	Center Of Seating Plane Location	5.95	6.75
P2	4 Feed Hole Pitch	50.30	51.30
T	Over All Tape Thickness	-	0.55
T1	Total Taped Package Thickness	-	1.42
T2	Carrier Tape Thickness	0.36	0.68
W	Tape Width	17.50	19.00
W1	Adhesive Tape Width	5.00	7.00
-	20 pcs Pitch	253	255

TO-92 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

Notes: 1. Controlling dimension: millimeters.
 2. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3. If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

Important Notice:

- All rights are reserved. Reproduction in whole or in part is prohibited without the prior written approval of CYStek.
- CYStek reserves the right to make changes to its products without notice.
- CYStek **semiconductor products are not warranted to be suitable for use in Life-Support Applications, or systems.**
- CYStek assumes no liability for any consequence of customer product design, infringement of patents, or application assistance.